

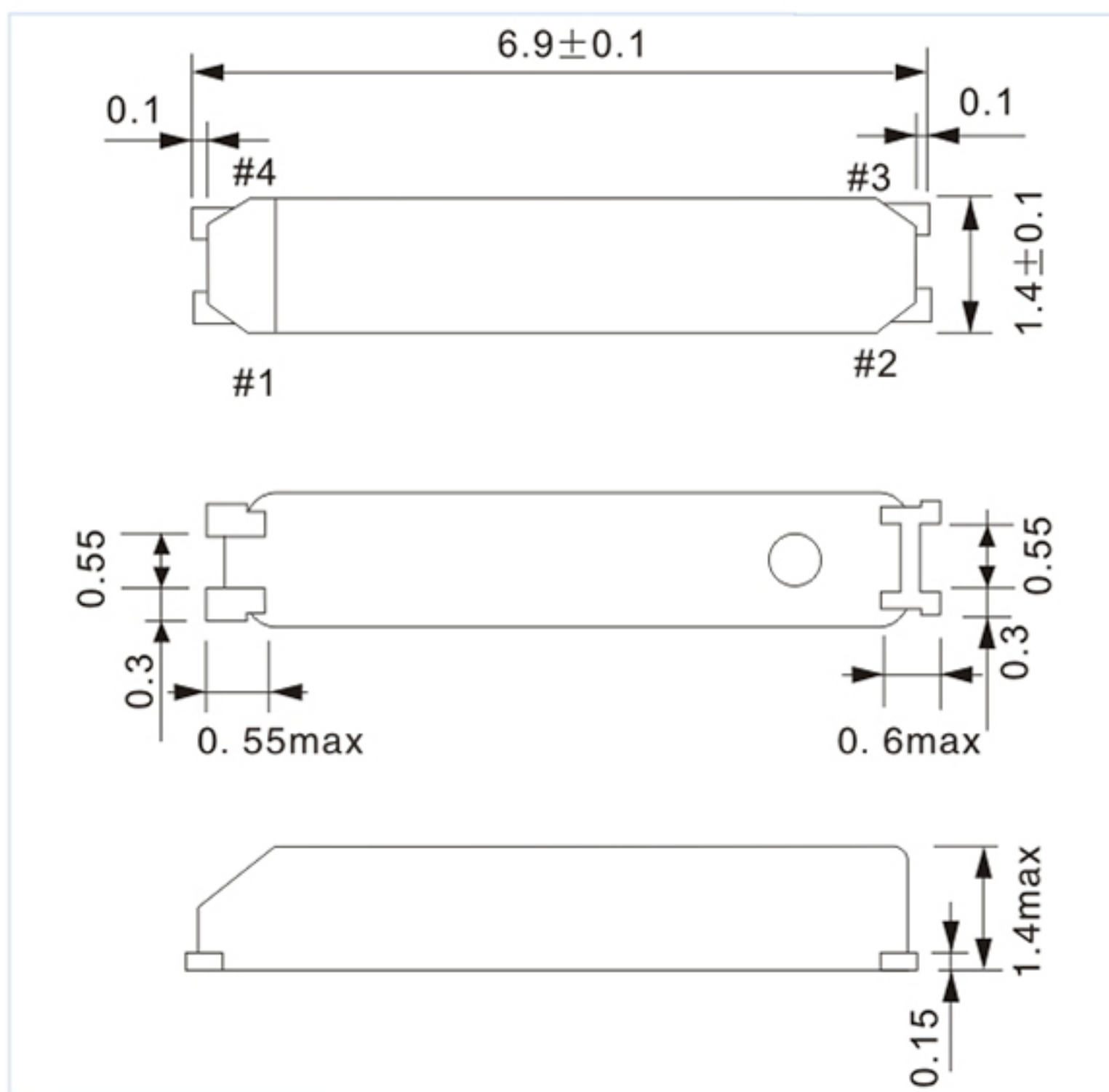
■ **特性 (FEATURES)**

小尺寸表面封装类型最适合高密度电路板
 Most appropriate for high-density circuit board by the small surface mount type
 嵌入具有热抵抗的柱状晶体带来高的稳定特性
 Embedded with heat resistant cylinder type crystal bring highly stable characteristics
 适合于小型移动通讯装备
 Suitable for small mobile telecommunications devices

■ **标准规格 (STANDARD SPECIFICATION)**

Item	Model	TMXLi-130	Conditions
频率范围 (Frequency Range)		32.768KHz	
负载电容 (Load Capacitance)		5-30pf	Need to specify
激励电平 (Drive Level)		1.0μW Max	
调整频差 (Frequency Tolerance)		± 10ppm~ ± 100ppm	
谐振电阻 (Series Resistance)		65KΩ Max	at 25°C Need to specify
拐点温度 (Turnover Temperature)		25 ± 5°C	
二次温度系数 (Temperature Coefficient)		[-0.035 ± 0.01]ppm/°C	
工作温度范围 (Operating Temperature Range)		-40~+85°C	
保存温度范围 (Storage Temperature Range)		-55~+125°C	at 25°C
动态电容 (Motional Capacitance)		0.0028pF Typical	
静态电容 (Shunt Capacitance)		0.8pF Typical	
老化率 (Aging[first year])		± 3ppm Max	25°C ± 3°C
绝缘阻抗 (Insulation Resistance)		500Mohm Min	
包装方式 (Packing unit)		3000pcs/reel .	

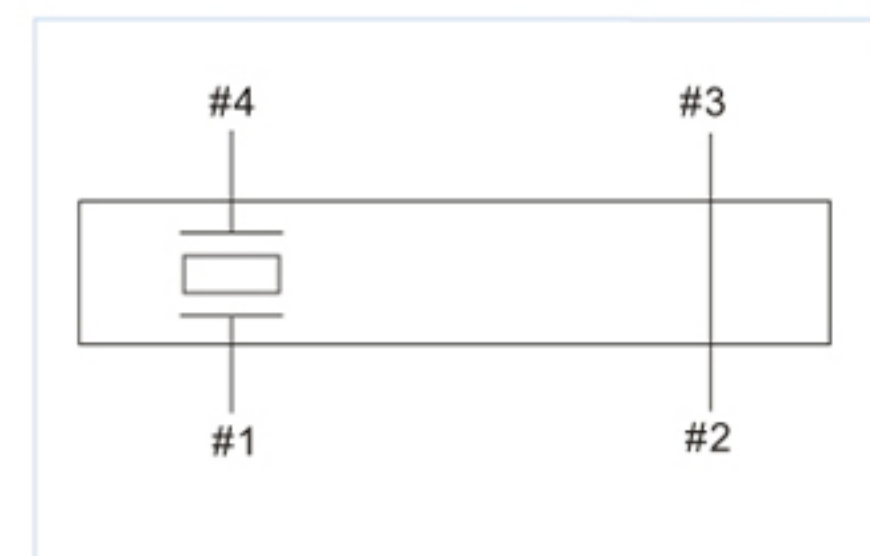
■ **OUTLINE DIMENSIONS (mm)**



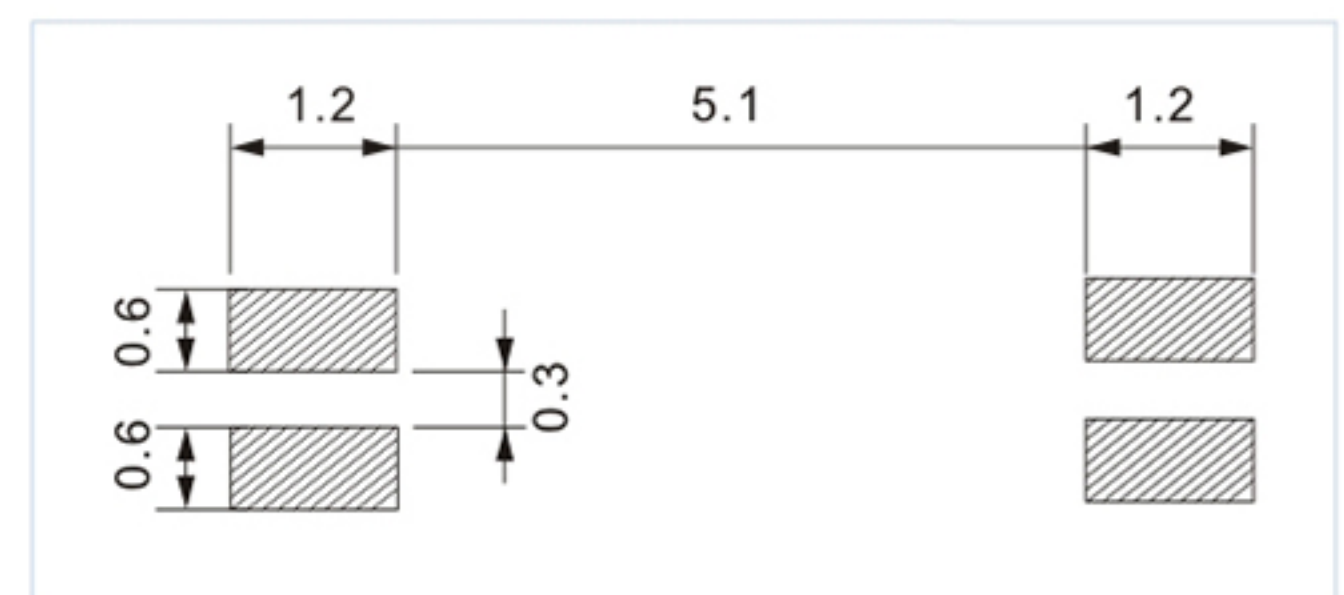
Remarks:

The part of the cylinder inside resin mold may be exposed, it dose not affect the characteristics of crystal unit.

■ **INTERNAL CONNECTIONS**



■ **SOLDER PATTERN**



说明:

树脂包装内的晶体外壳有可能会有部分露出，这不影响产品的性能。